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(71) Applicant *(for all designated States except US)*: **LAM RESEARCH CORPORATION** [US/US]; 4650 Cushing Parkway, Fremont, California 94538 (US).

(72) Inventors; and
(75) Inventors/Applicants *(for US only)*: **ALLEN-BLANCHETTE, Christine** [US/US]; 4650 Cushing Parkway, Fremont, CA 94538 (US). **RODNICK, Matt** [US/US]; 4650 Cushing Parkway, Fremont, CA 94538 (US).

(74) Agent: **NGUYEN, Joseph A.**; P.O. Box 700640, San Jose, CA 95170 (US).

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(54) Title: SYSTEMS AND METHODS FOR CALIBRATING END EFFECTOR ALIGNMENT IN A PLASMA PROCESSING SYSTEM

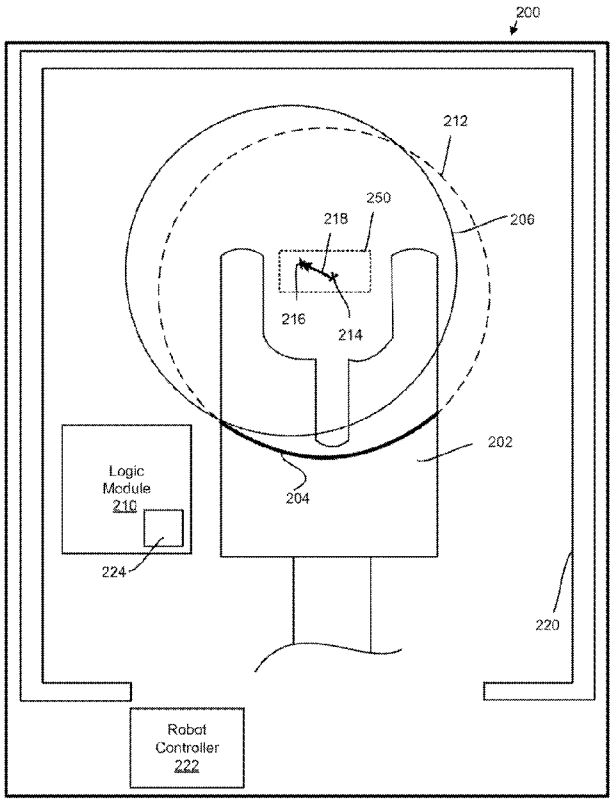


FIG. 2

(57) Abstract: A method for calibrating alignment of an end effector with respect to a chuck in a plasma processing system is provided. The method including positioning the end effector over the chuck and taking a still image of the chuck and the end effector. The method including processing the still image to ascertain the center of the chuck and the end effector-defined center defined by the end effector. The method including determining a positional difference between the end effector-defined center and the center of the chuck. The method also including providing the positional difference to a robot controller to control a robot mechanism to adjust the positional difference when the end effector transports a wafer.

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